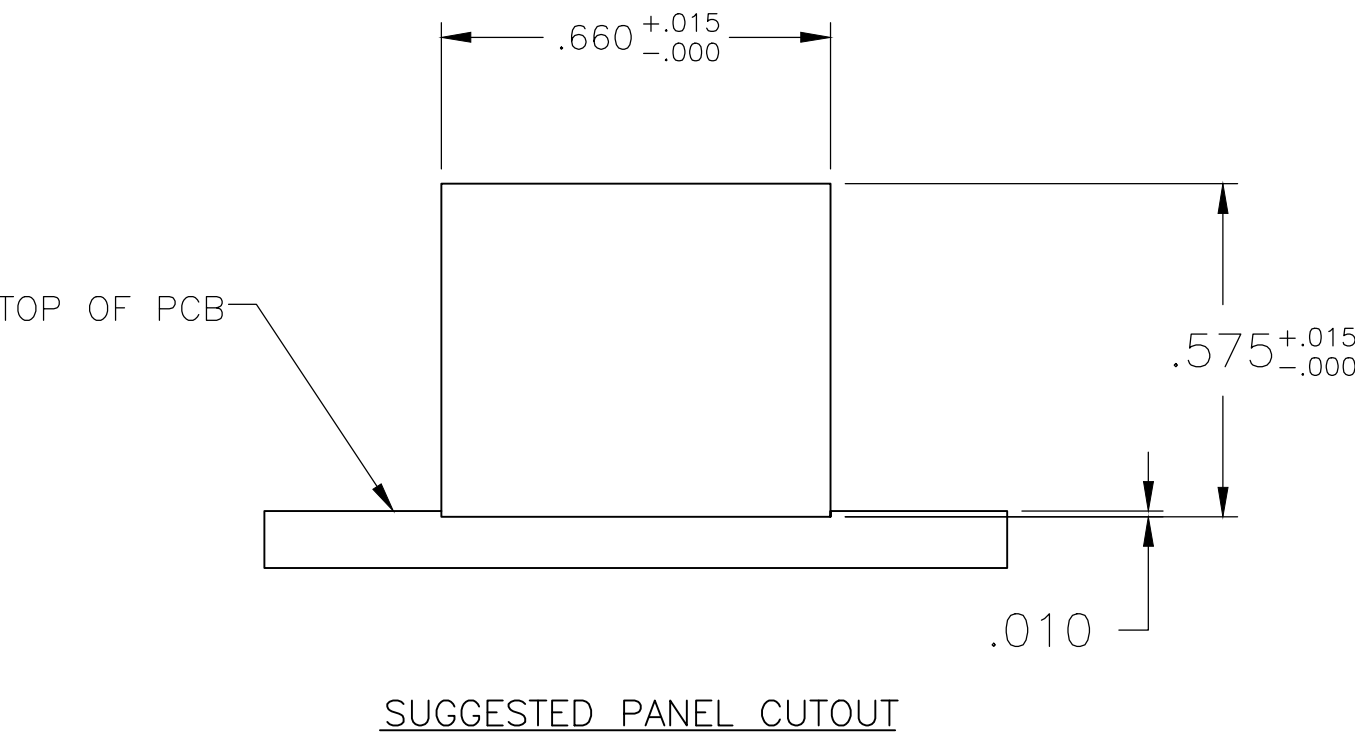
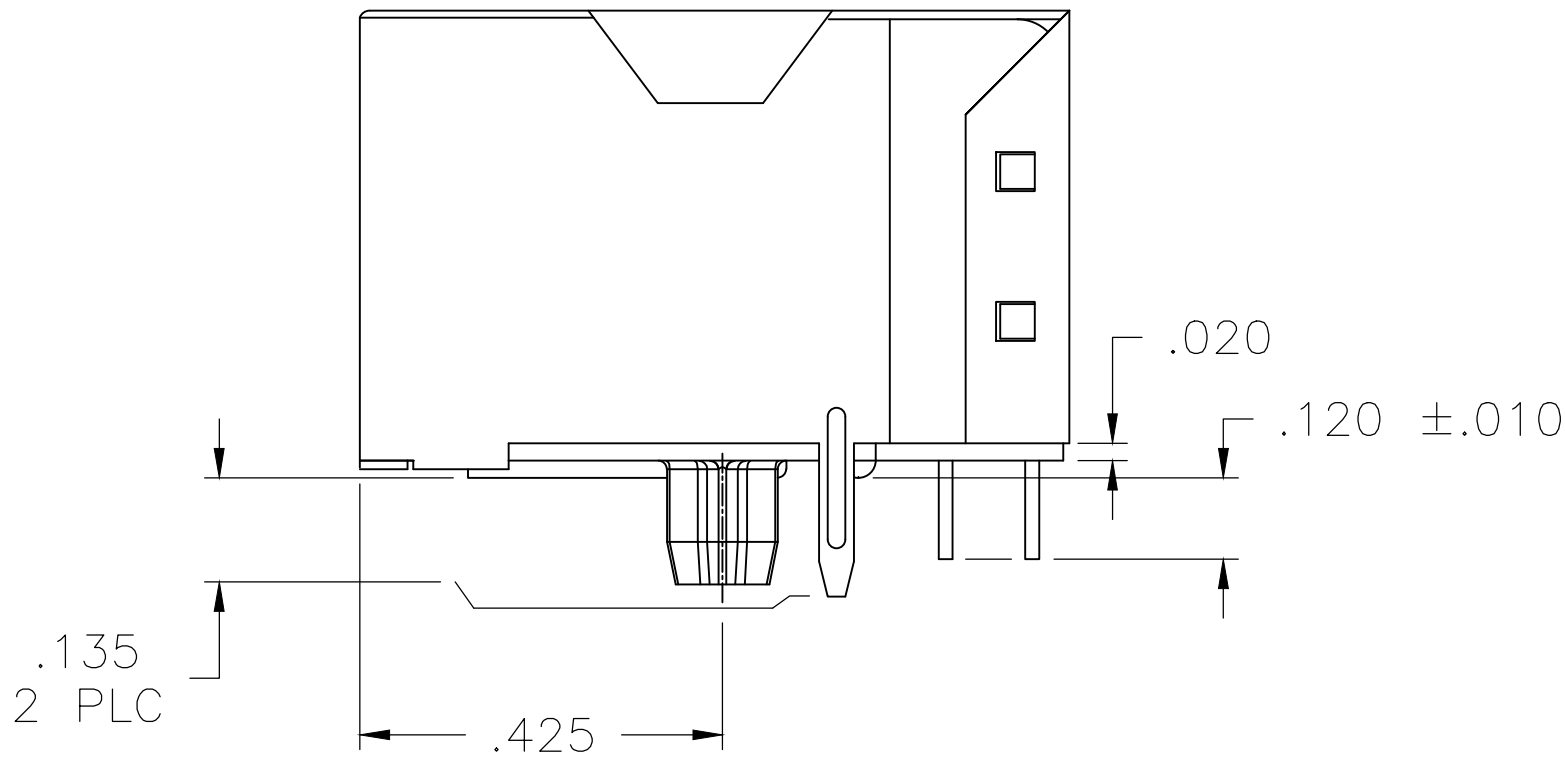
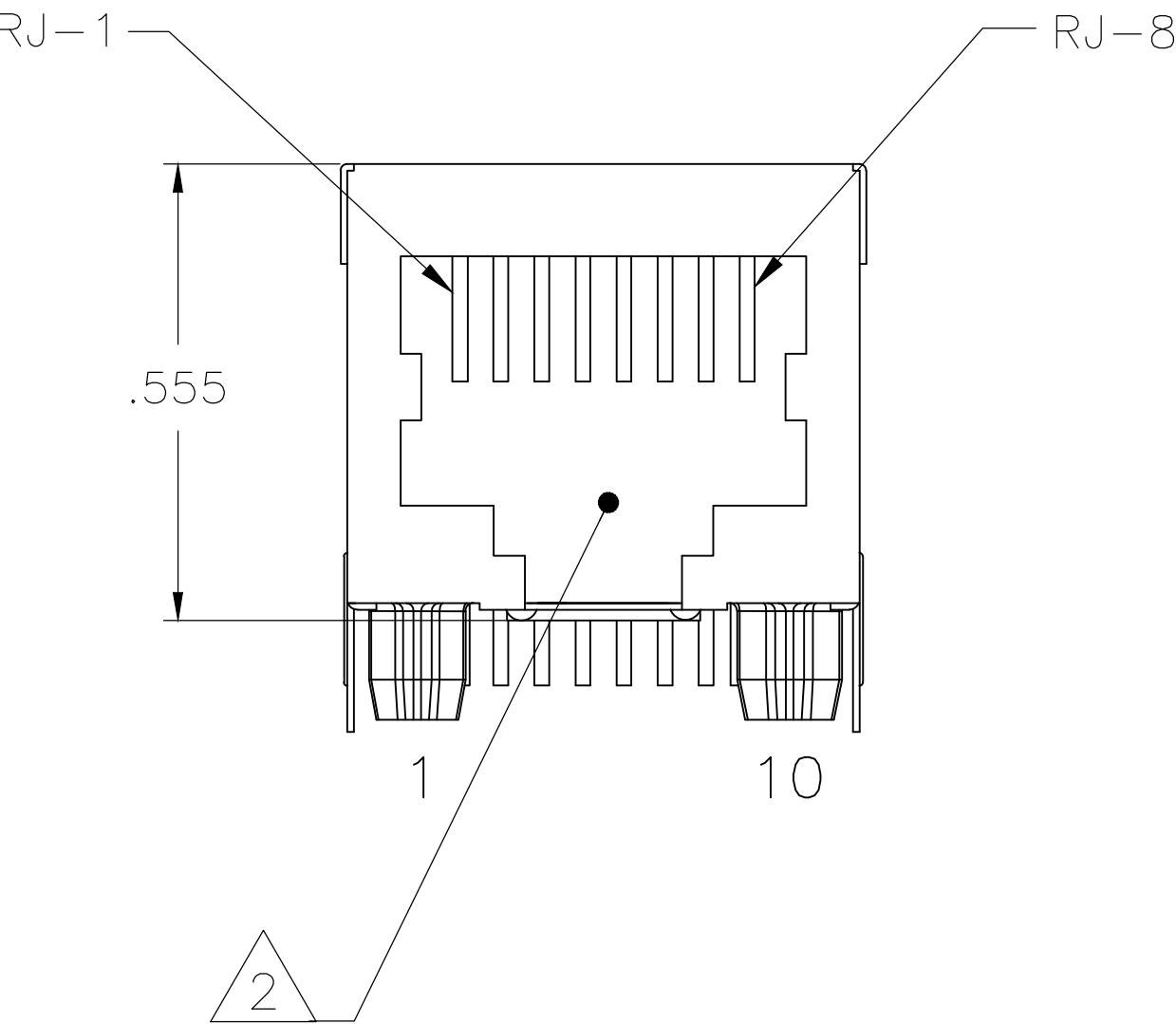
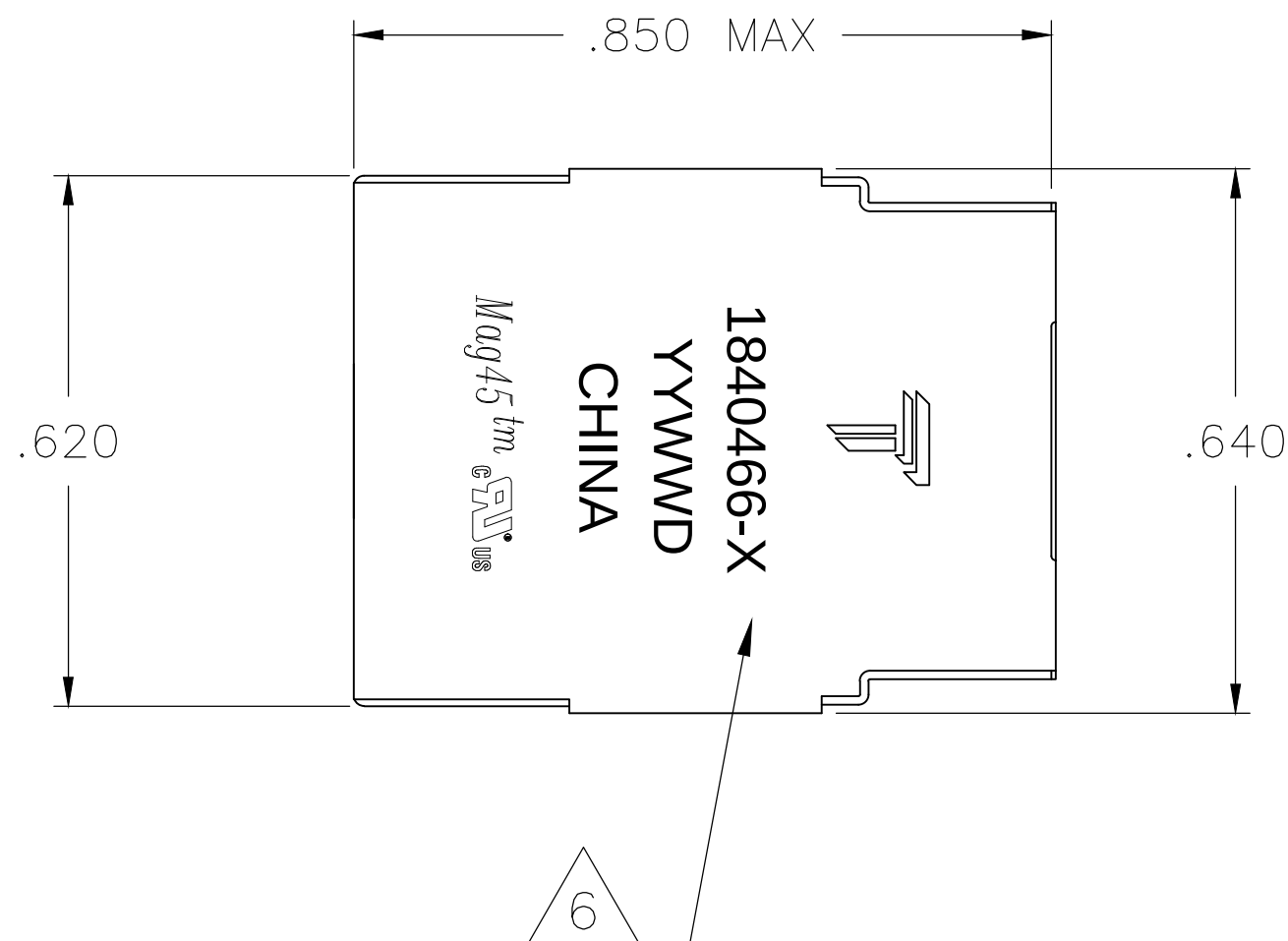
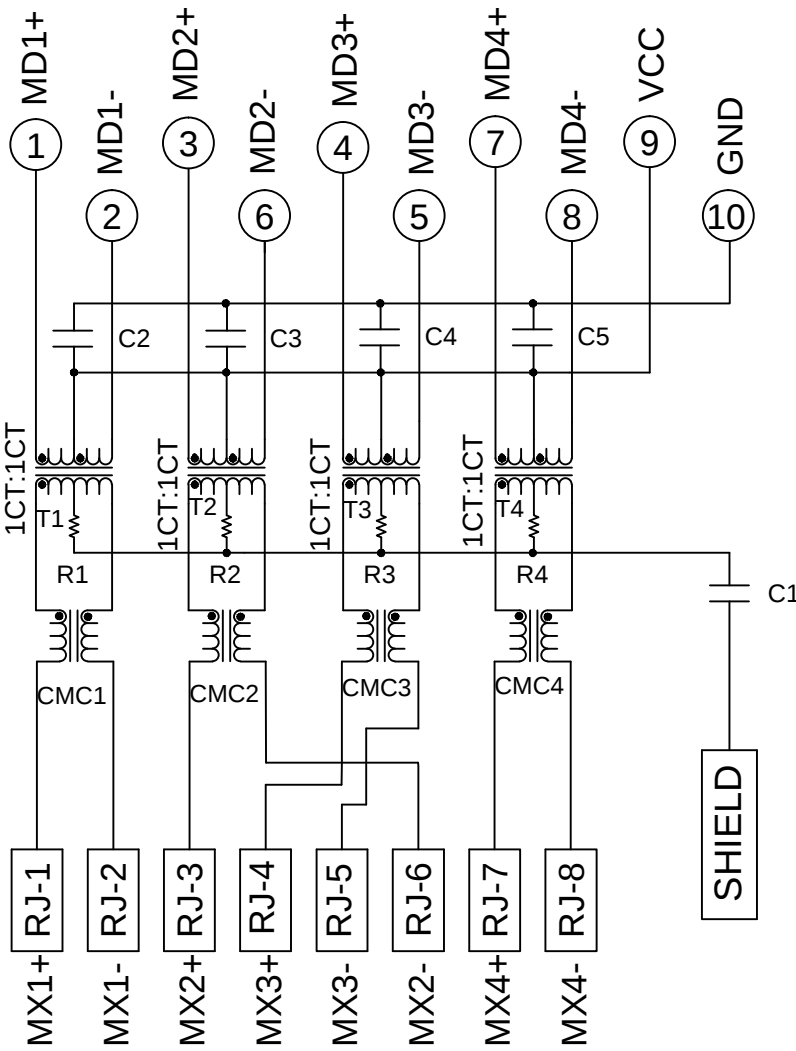


MECHANICAL:



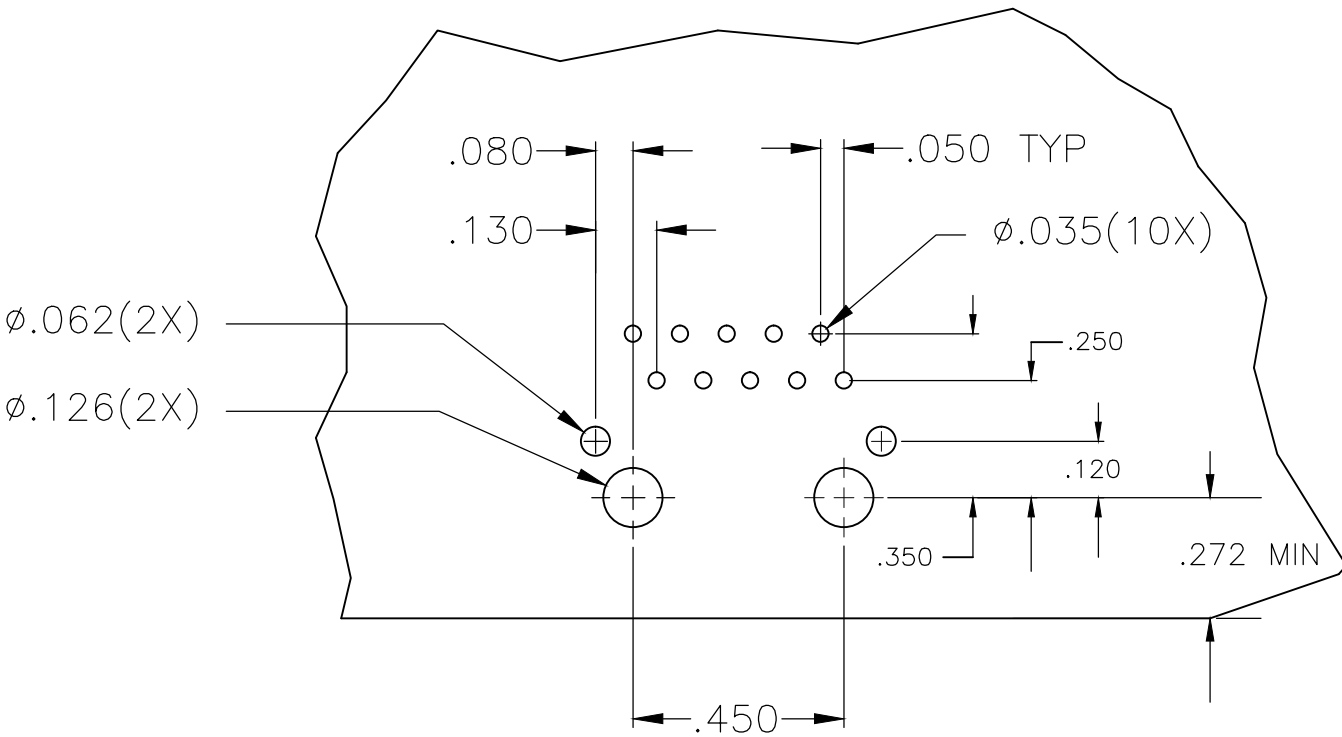
4G06P2 GIGABIT CIRCUIT



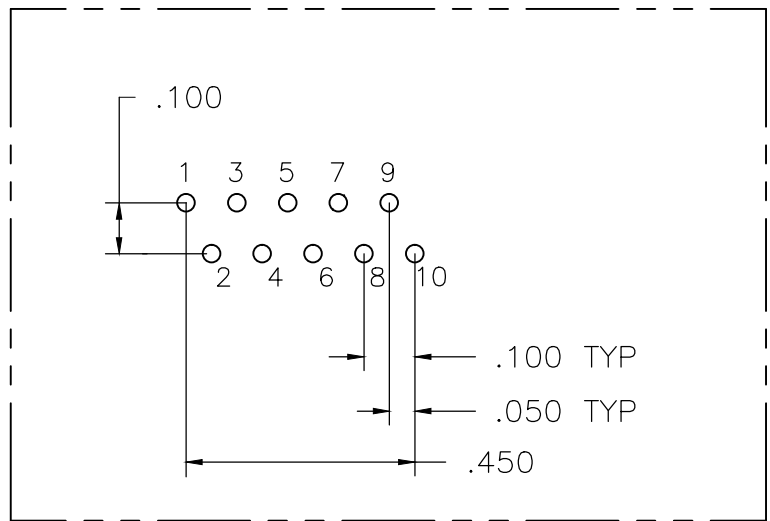
R1-R4 = 75 OHMS, 1/16W, 5% RESISTORS
C1 = 1000pF, 3kV CAPACITOR
C2 - C5 = 0.1uF, 10%, 50V, X7R CAPACITOR

NOTES:

- ⚠ MATERIALS
- HOUSING: THERMOPLASTIC, FLAMMABILITY RATING UL 94V-0.
 - SHIELD: BRASS C26800 0.008 INCH THICK, PREPLATED WITH 30uINCH MIN SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100uINCH MIN SAC SOLDER.
 - CONTACTS: PHOSPHOR BRONZE 0.0157 X 0.018", 50uINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECTIVE 50uINCH MIN HARD GOLD FINISH PLATE.
 - SOLDER TAILS: 100uINCH MIN MATTE TIN AND/OR SAC SOLDER DIP.
- ⚠ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 SUB PART F.
- ⚠ MAGNETICS
- APPLICATION: 10/100/1000 BASE-T
 - IMPEDANCE: 100 OHMS
 - TURNS RATIO (CHIP:CABLE): 1:1 ALL FOUR PAIRS
 - OPEN CIRCUIT INDUCTANCE (OCL): 350uH MIN. @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO +70°C, ALL FOUR PAIRS
 - ALL FOUR PAIRS BI-DIRECTIONAL
 - PERFORMANCE @ 25°C:
 - INSERTION LOSS (IL): 1.1dB MAX. FROM 0.5MHz TO 100MHz
 - RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 40MHz
 - 12-20LOG(f/80)dB MIN. FROM 40.1MHz TO 100MHz
 - CROSSTALK ATTENUATION: 35dB MIN. FROM 0.5MHz TO 40MHz
 - 33-20LOG(f/50)dB MIN. FROM 40.1MHz TO 100MHz
 - COMMON MODE REJECTION RATIO (CMRR):30dB MIN. FROM 0.5MHz TO 100MHz
 - ISOLATION VOLTAGE: COMPLIES WITH IEEE802.3 2002, PARA 40.6.1.1, ITEM a.
4. OPERATING TEMPERATURE: FROM 0°C TO +70°C.
- ⚠ INDICATED MAGNETIC CONNECTIONS ARE SYMMETRICAL TO SUPPORT AUTO-MDI/MDIX.
- ⚠ TRP CONNECTOR LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
7. THE PART IS RECOMMENDED FOR WAVE SOLDERING PROCESS,PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK WAVE SOLDERING TEMPERATURE IS 260°C MAX,10 SECONDS MAX.



SUGGESTED PCB LAYOUT
COMPONENT SIDE



PIN DESIGNATIONS